### Switch Mode Power Rectifier

These state-of-the-art devices are designed for use in negative switching power supplies, inverters and as free wheeling diodes. Also, used in conjunction with common cathode dual Ultrafast Rectifiers, makes a single phase full-wave bridge.

#### **Features**

- Common Anode Dual Rectifier (8.0 A per Leg or 16 A per Package)
- Ultrafast 35 Nanosecond Reverse Recovery Times
- Exhibits Soft Recovery Characteristics
- High Temperature Glass Passivated Junction
- Low Leakage Specified @ 150°C Case Temperature
- Current Derating @ Both Case and Ambient Temperatures
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Complement to MUR1620CT and MURB1620CT Common Cathode Device
- ESD Ratings:
  - Machine Model = C > 400 V
  - ◆ Human Body Model = 3B (> 16,000 V)
- NRVU Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices\*

### **Mechanical Characteristics:**

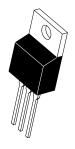
- Case: Epoxy, Molded
- Weight: MUR1620CTR: 1.9 Grams (Approximately) MURB1620CTR: 1.7 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



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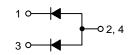
# **ULTRAFAST RECTIFIER**16 AMPERES, 200 VOLTS





TO-220AB CASE 221A STYLE 7

D<sup>2</sup>PAK CASE 418AJ



### **MARKING DIAGRAMS**





TO-220AB

D<sup>2</sup>PAK

U1620R = Device Code
KAK = Diode Polarity
A = Assembly Location
Y - Year

Y = Year WW = Work Week G = Pb-Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### MAXIMUM RATINGS (Per Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	200	V
Average Rectified Forward Current (Rated V <sub>R</sub> , T <sub>C</sub> = 160°C) Per Leg Per Total Device	I <sub>F(AV)</sub>	8.0 16	А
Peak Repetitive Surge Current (Rated V <sub>R</sub> , Square Wave, 20 kHz, T <sub>C</sub> = 140°C) Per Diode	I <sub>FM</sub>	16	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	100	А
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	2.0	°C/W
Thermal Resistance, Junction-to-Ambient (D <sup>2</sup> PAK)	$R_{ heta JA}$	45	°C/W

### **ELECTRICAL CHARACTERISTICS** (Per Leg)

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 1) ( $i_F = 8.0 \text{ Amps}, T_C = 25^{\circ}\text{C}$ ) ( $i_F = 8.0 \text{ Amps}, T_C = 150^{\circ}\text{C}$ )	VF	1.2 1.1	V
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, T <sub>C</sub> = 25°C) (Rated dc Voltage, T <sub>C</sub> = 150°C)	İR	5.0 500	μΑ
Maximum Reverse Recovery Time (I <sub>F</sub> = 1.0 Amp, di/dt = 50 Amps/μs)	t <sub>rr</sub>	85	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MUR1620CTRG	TO-220 (Pb-Free)	50 Units / Rail
MURB1620CTRG	D <sup>2</sup> PAK-3 (Pb-Free)	50 Units / Rail
MURB1620CTRT4G	D <sup>2</sup> PAK-3 (Pb-Free)	800 / Tape & Reel
NRVUB1620CTRT4G	D <sup>2</sup> PAK-3 (Pb-Free)	800 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>1.</sup> Pulse Test: Pulse Width = 5.0 ms, Duty Cycle  $\leq 10\%$ .

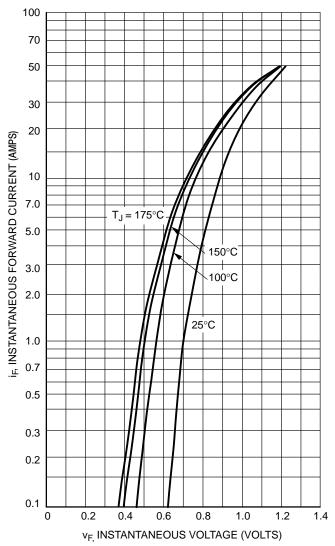


Figure 1. Typical Forward Voltage (Per Leg)

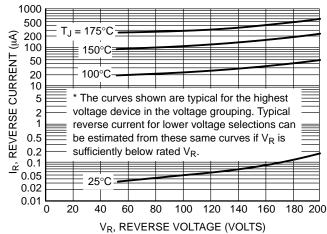


Figure 2. Typical Reverse Current\* (Per Leg)

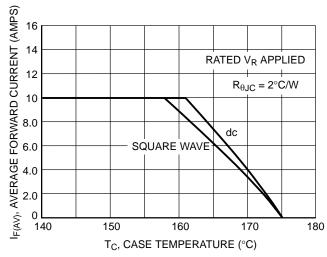
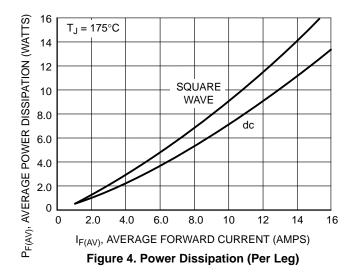


Figure 3. Current Derating, Case (Per Leg)



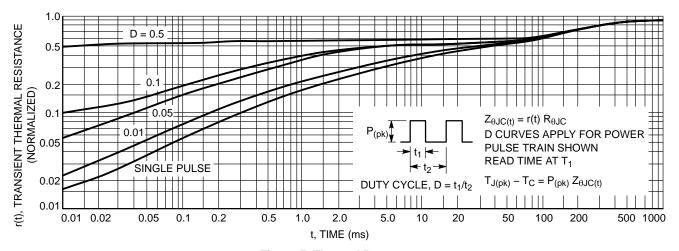


Figure 5. Thermal Response

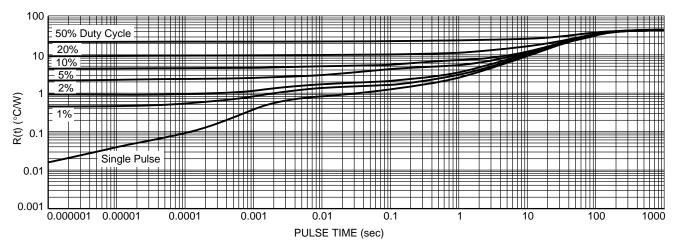


Figure 6. Thermal Response, Junction-to-Ambient

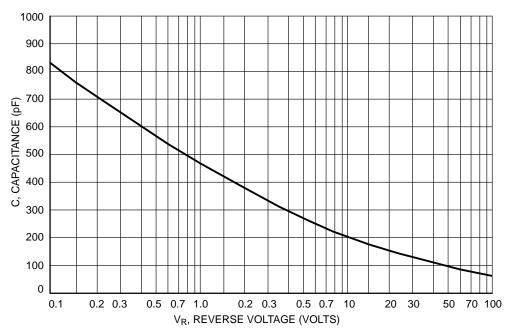
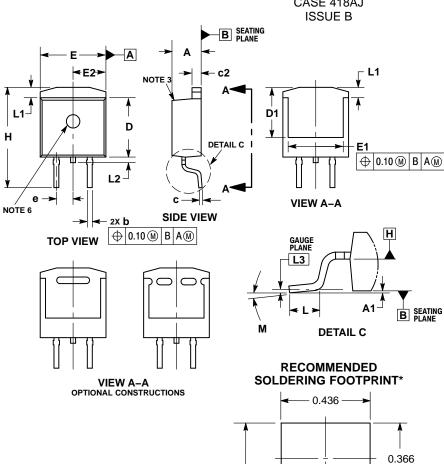


Figure 7. Typical Capacitance (Per Leg)

### PACKAGE DIMENSIONS

### D<sup>2</sup>PAK-3 (TO-263, 3-LEAD) CASE 418AJ



0.653

0.063

#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

  2. CONTROLLING DIMENSION: INCHES.

  3. CHAMFER OPTIONAL

  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.

  5. THERMAL PAD CONTOUR IS OPTIONAL WITHIN DIMENSIONS E, L1, D1 AND E1.

  6. OPTIONAL MOLD FEATURE

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.160	0.190	4.06	4.83
A1	0.000	0.010	0.00	0.25
b	0.020	0.039	0.51	0.99
С	0.012	0.029	0.30	0.74
c2	0.045	0.065	1.14	1.65
D	0.330	0.380	8.38	9.65
D1	0.260		6.60	
Е	0.380	0.420	9.65	10.67
E1	0.245		6.22	
е	0.100 BSC		2.54 BSC	
Н	0.575	0.625	14.60	15.88
L	0.070	0.110	1.78	2.79
L1		0.066		1.68
L2		0.070		1.78
L3	0.010	BSC	0.25 BSC	
М	0°	8°	0°	8°

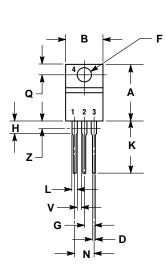
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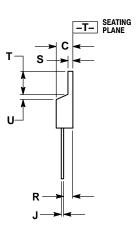
0.169

0.100 PITCH DIMENSIONS: INCHES

### PACKAGE DIMENSIONS

**TO-220**CASE 221A-09
ISSUE AH





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
   V14 FM 1082
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN MAX	
Α	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
7		0.080		2 04

STYLE 7:

PIN 1. CATHODE

- 2. ANODE
- B. CATHODE
- 4. ANODE

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